



VMDSEMI

**VUTL003R046NA**

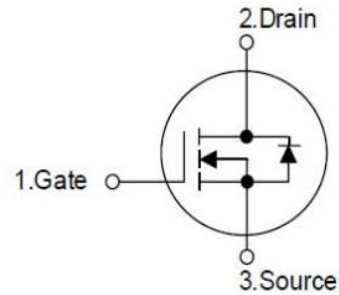
**Datasheet**



VMDSEMI

**4.6mΩ, 30V, N-Channel Power MOSFET**
**VUTL003R046NA**
**General Description**
**Symbol**

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	$I_D$
30V	4.6mΩ@10V	80A
	8mΩ@4.5V	



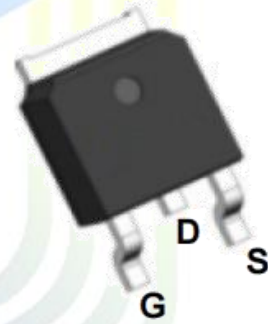
Symbol of VUTL003R046NA

**Features**

- Excellent package for good heat dissipation
- Advanced Trench technology
- Low Gate Charge

**Application**

- Power switching application
- Load Switch
- Hard switched and high frequency circuits

**Package Type**


TO-252

Package Type of VUTL003R046NA

**Ordering Information**

Product Name	Package
VUTL003R046NA	TO-252

**Absolute Maximum Ratings**( $T_A=25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		$V_{DS}$	30	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>Note 1</sup>	$T_C=25^\circ\text{C}$	$I_D$	80	A
Pulsed Drain Current <sup>Note 2</sup>	$T_C=25^\circ\text{C}$	$I_{DM}$	320	A
Max Power Dissipation <sup>Note 3</sup>	$T_C=25^\circ\text{C}$	$P_D$	62	W
Avalanche Energy, Single Pulse <sup>Note 4</sup>		$E_{AS}$	144	mJ
Operation Junction temperature		$T_J, T_{SGT}$	-55 to 150	$^\circ\text{C}$

**Thermal Resistance**

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	-	1.985	-	$^\circ\text{C/W}$

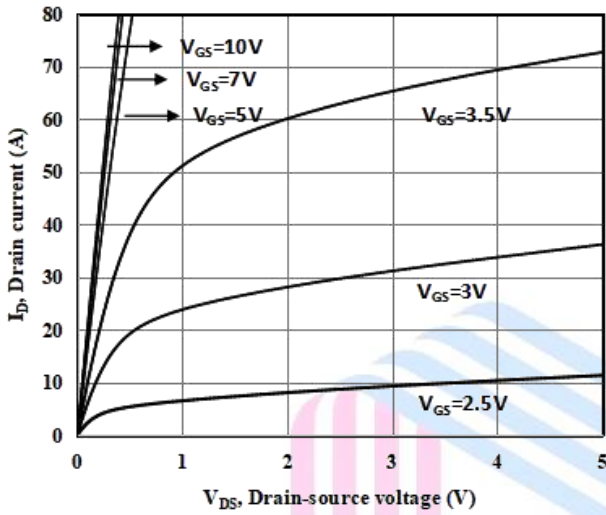
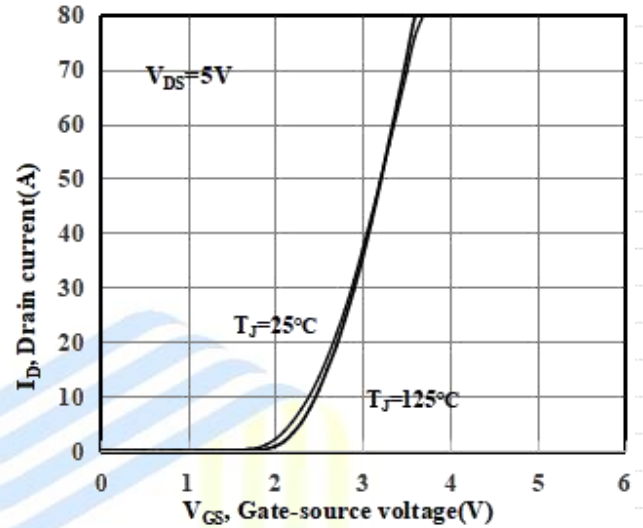
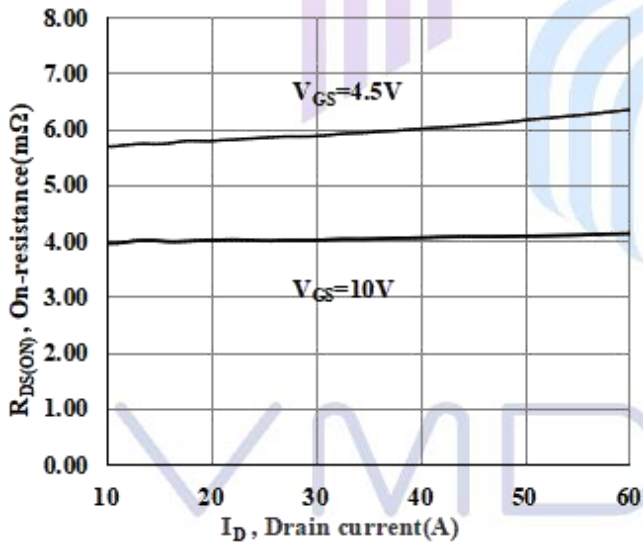
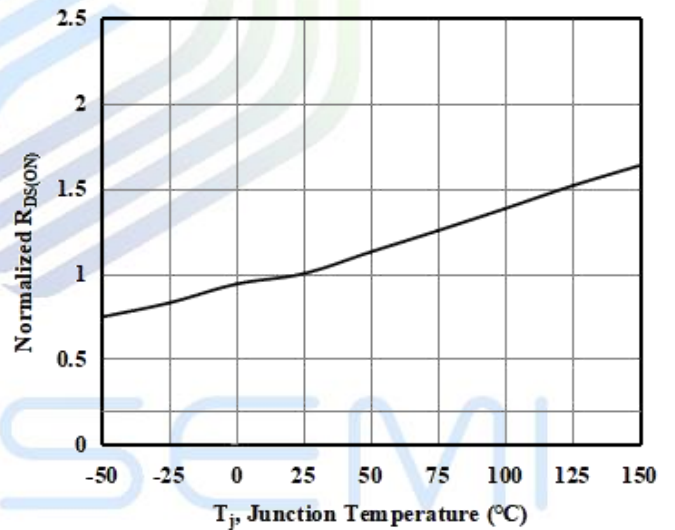
Notes:

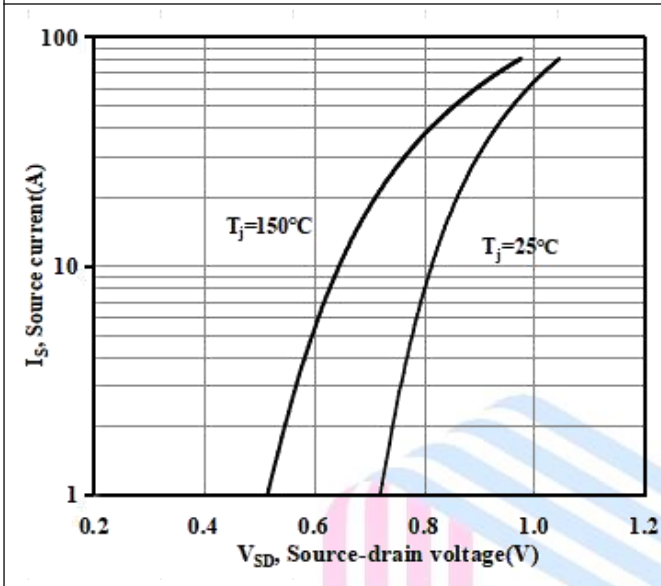
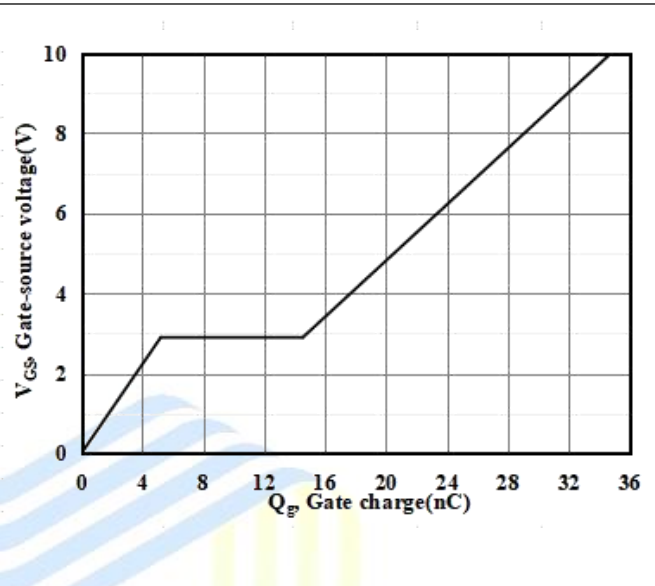
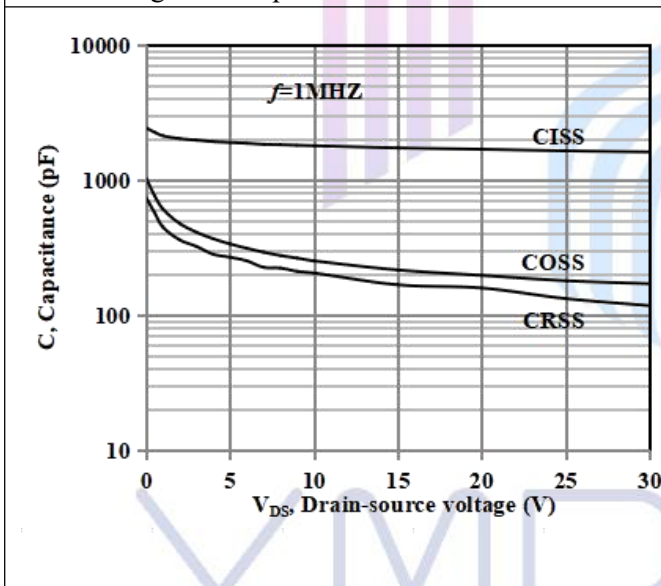
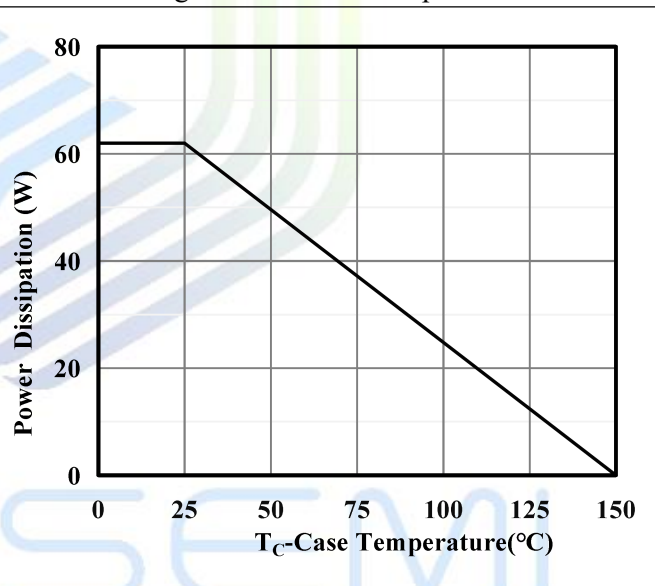
- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3)  $P_D$  is based on max. junction temperature, using junction-case thermal resistance.
- 4)  $V_{DD}=24\text{V}, V_{GS}=10\text{V}, L=0.5\text{mH}$ , starting  $T_J=25\text{ }^\circ\text{C}$ .

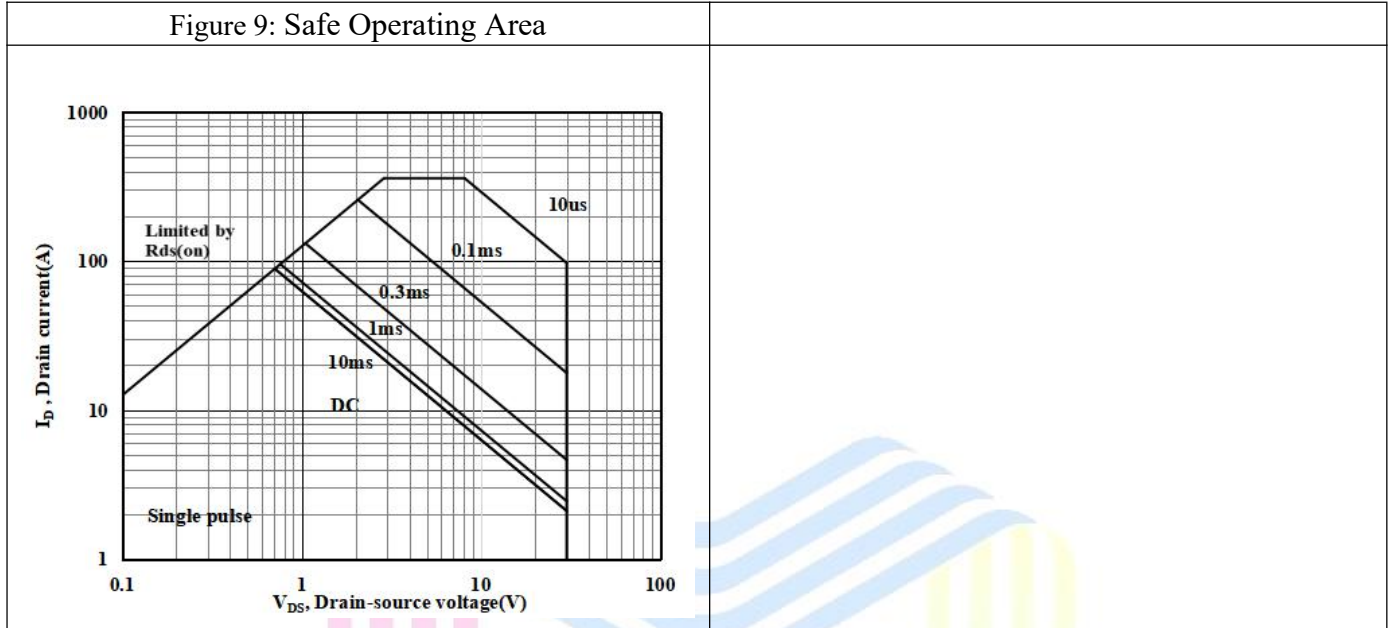
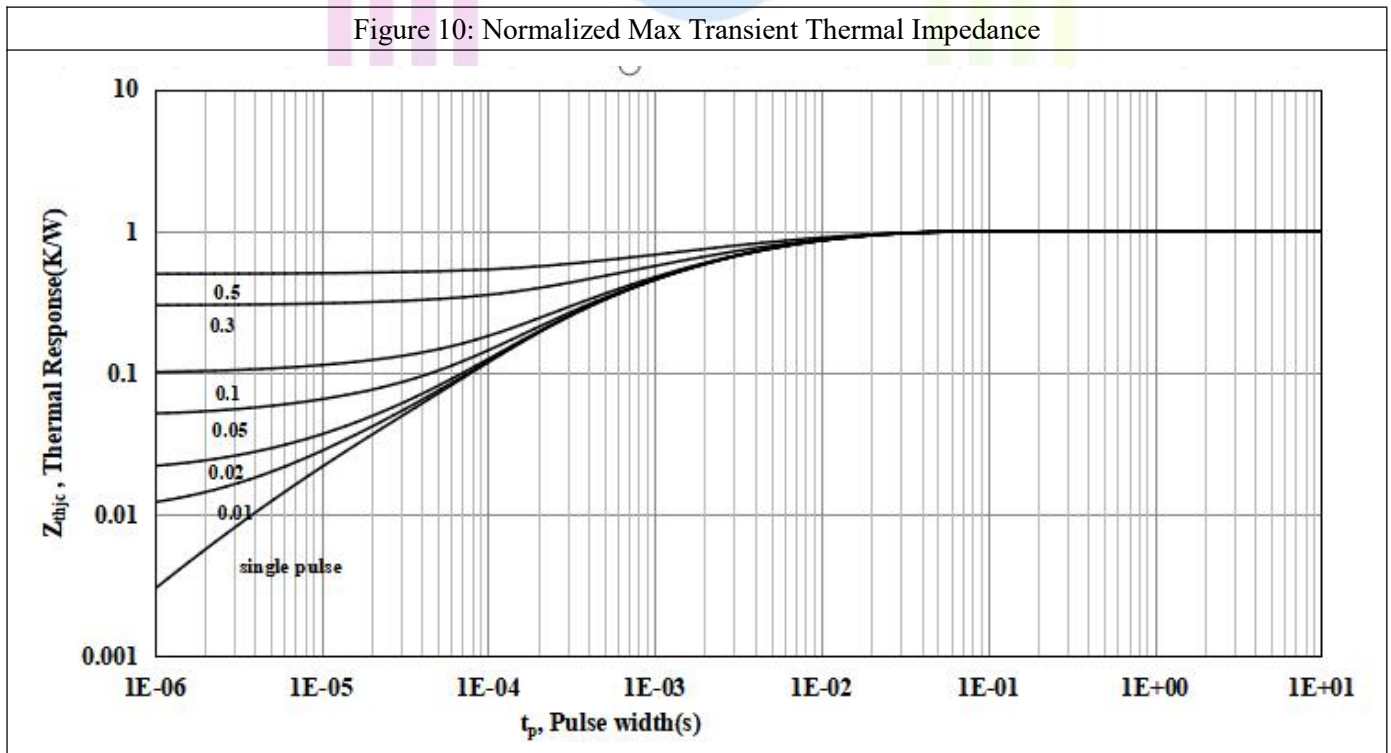
**Electrical Characteristics**( $T_A=25\text{ }^\circ\text{C}$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=30V, V_{GS}=0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.5	2.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=30A$	-	3.98	4.6	mΩ
		$V_{GS}=4.5V, I_D=20A$	-	5.8	8	
Gate Resistance	$R_G$	f=1MHz, Open Drain	-	2.17	-	Ω
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{GS}=0V$	-	1725	-	pF
Output Capacitance	$C_{oss}$	$V_{DS}=15V$	-	214	-	pF
Reverse Transfer Capacitance	$C_{rss}$	f=1MHz	-	168	-	pF
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=15V$	-	7.6	-	ns
Rise Time	$t_r$	$V_{GS}=10V$	-	71.6	-	
Turn-off Delay Time	$t_{d(off)}$	$I_D=30A$	-	28.6	-	
Fall Time	$t_f$	$R_G=3\Omega$	-	102.6	-	
<b>Gate Charge Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{GS}=10V$	-	34.8	-	nC
Gate to Source Charge	$Q_{gs}$	$V_{DS}=25V$	-	5.2	-	
Gate to Drain Charge	$Q_{gd}$	$I_D=30A$	-	9.3	-	
<b>Reverse Diode Characteristics</b>						
Drain-Source Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=30A$	-	0.87	1.2	V
Reverse Recovery Time	$t_{rr}$	$V_{DD}=20V, I_F=20A$	-	13.5	-	ns
Reverse Recovery Charge	$Q_{rr}$	di/dt=100A/us	-	6.8	-	nC

### Typical Performance Characteristics

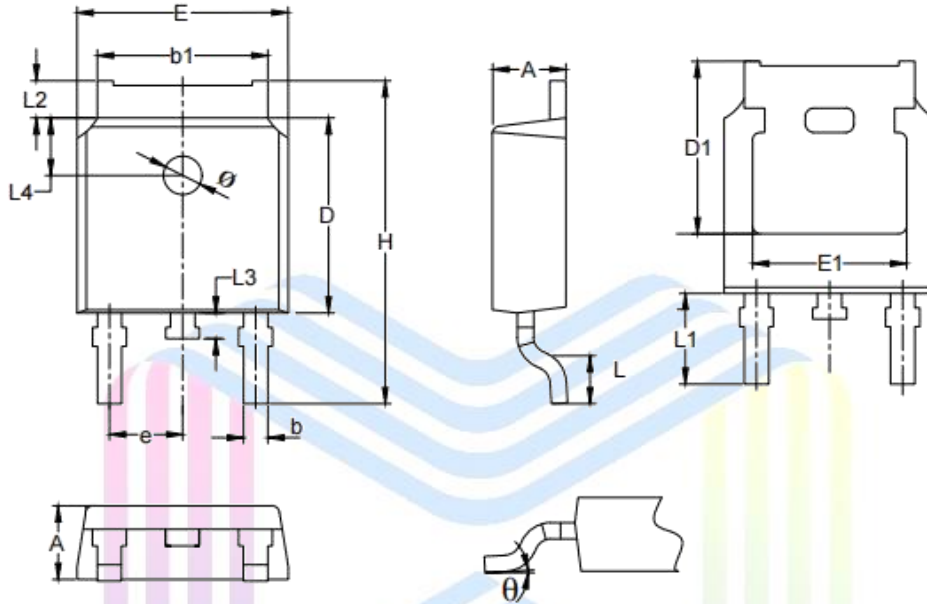
**Figure 1: Typ. Output Characteristics**

**Figure 2: Typ. Transfer Characteristics**

**Figure 3: Typ. On-Resistance vs. Drain Current**

**Figure 4: On-Resistance vs. Temperature**


**Figure 5: Is vs Source to Drain Voltage**

**Figure 6: Gate Charge Characteristics**

**Figure 7: Capacitance Characteristics**

**Figure 8: Power dissipation**


**Figure 9: Safe Operating Area**

**Figure 10: Normalized Max Transient Thermal Impedance**


## Mechanical Dimensions

### TO-252 Package Information



SYMBOL	MILLIMETERS	
	MIN	MAX
A	2.2	2.4
A1	0	0.127
A2	-	-
b	0.66	0.9
b1	5.1	5.5
c	0.43	0.61
D	5.95	6.22
D1	5.3REF	
E	6.4	6.75
E1	4.8REF	
e	2.286BSC	
H	9.4	10.5
L	1.38	2
L1	2.9REF	
L2	0.88	1.28
L3	0.5	1
L4	1.8REF	
θ	0°	8°



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